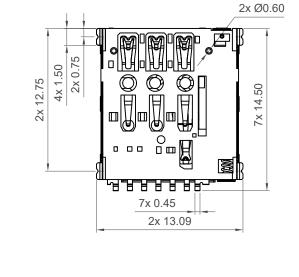
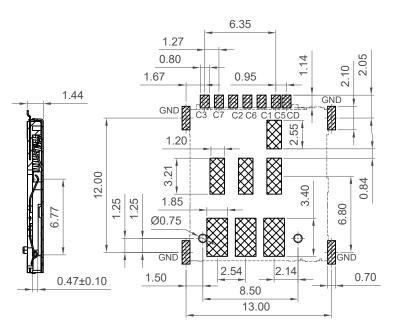
0.10 4.83 0.95 1.27 stroke position Card lock position (A 13.72 Push 2x 2.00 ref. ref. 65 50 0 Ø A Ø

F

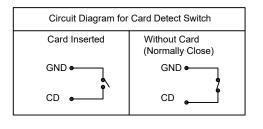
F

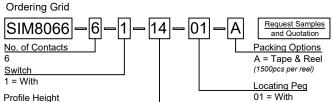






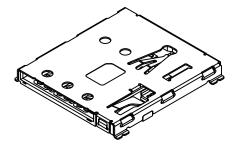
Recommended PCB Layout (Viewed from Component Side - Tolerance:±0.05mm) Solder Area X Keep Out Area C Component Outline





14 = 1.44mm

4.20 ref. Card eject position



Specifications

## Material

Housing&Slide : High Temperature Thermoplastic, UL94V-0, Black Contact Terminal: Copper Alloy Metallic Shell: Stainless Steel Spring: SWP-B Link: Stainless Steel

## Plating

Contact : Contact Area: Gold Flash over Nickel Soldering Tail: Gold Flash over Nickel Shell: Soldering Tail: Gold Flash over Nickel

Spring&Link: Cleaning

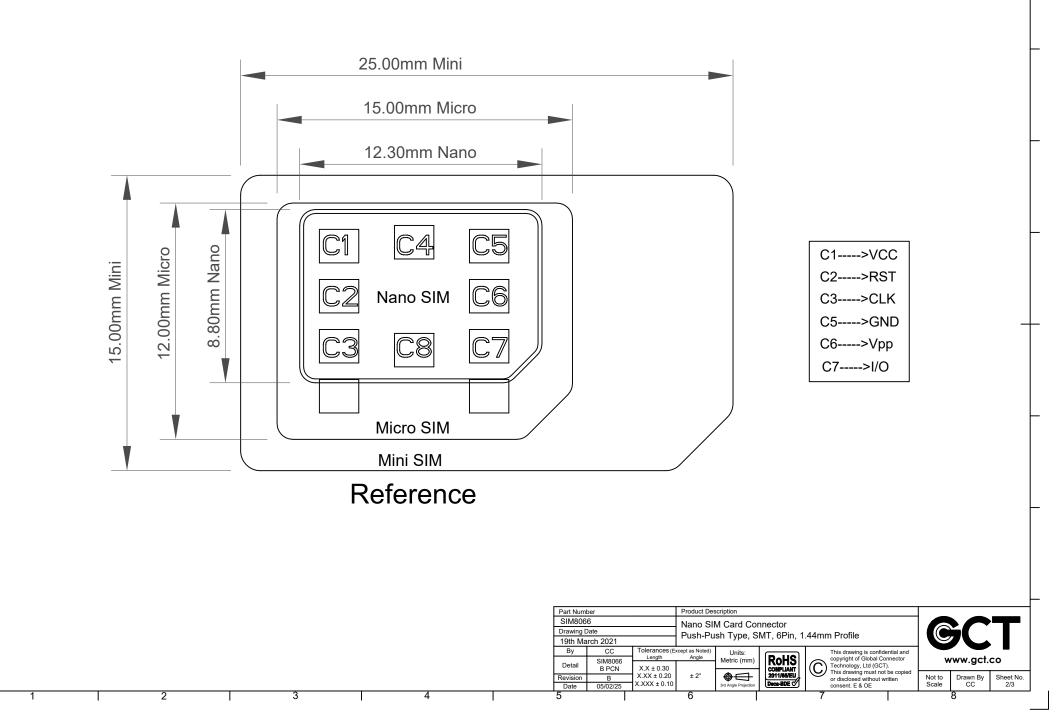
## Electrical

Voltage rating: 30V AC/DC Current Rating: 1.0 Amp AC/DC Max. Contact Resistance: Signal contact: 100 m $\Omega$  Max. CD to GND: 200 m $\Omega$  Max. Dielectric Withstanding Voltage:500V AC (60 Sec Min. )

Insulation Resistance: 1000 M $\Omega$  Min.@500V DC

Mechanical & Environmental Operating Temperature: -40°C to +85°C Durability: 5,000 cycles

Part Number			Product Description								
SIM806	6		Nano SIM Card Connector								, <b>Experie</b>
Drawing D	Date		Push-Push Type, SMT, 6Pin, 1.44mm Profile								
19th March 2021											
By	CC		plerances (Except as Noted)				This drawing is confide		www.gct.co		
Detail	SIM8066 B PCN	X.X ± 0.30		Metric (mm)		(n) Te	copyright of Global Connector Technology, Ltd (GCT). This drawing must not be copied				
Revision	В	X.XX ± 0.20			2011/65/EU	or disclosed without w			Not to Scale	Drawn By	Sheet No.
Date	05/02/25	X.XXX ± 0.10		3rd Angle Projection	Deca-BDE		consent. E & OE	)E		CC	1/3
5		6			7			8			



F

B

